

INFORMATION DISCLOSURE CITATION
(Use several sheets if necessary)

Docket Number (Optional)

TWI-30400

Application Number

10/074,561

Applicant(s)

Abdurrahman Sezginer et al.

Filing Date

February 12, 2002

Group Art Unit

2877

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE
38	AA	5,712,707	01/27/1998	Ausschnitt et al.	356	401	11/20/1995
	AB	5,795,687	08/18/1998	Yasuda	430	22	02/23/1996
	AC	5,805,290	09/08/1998	Ausschnitt et al.	356	401	05/02/1996
	AD	6,130,750	10/10/2000	Ausschnitt et al.	356	401	08/28/1997
	AE	6,458,605	10/01/2002	Stirton	438	7	06/28/2001
	AF	2003/0190793	10/09/2003	Brill et al.	438	401	09/20/2001

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	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
38	AG	62157295	06/23/1987	Japan	H01L	21/30	Abstract	
	AH	0 192 656 B1	05/23/1990	EPO	G01B	11/06		
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	AJ	WO 02/25723 A2	03/28/2002	PCT	H01L	21/66		

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38	AK	C.C. Baum et al., "Scatterometry for Post-etch Polysilicon Gate Metrology", <i>Part of the SPIE Conference on Metrology, Inspection and Process Control for Microlithography XIII</i> , Santa Clara, CA, March 1999, SPIE Vol. 3677, pp. 148-158.
	AL	J. Bischoff et al., "Single feature metrology by means of light scatter analysis", <i>SPIE</i> , Vol. 3050 (1997), pp. 574-585.
	AM	J. Bischoff et al., "Diffraction analysis based characterization of very fine gratings", <i>SPIE</i> , Vol. 3099 (1997), pp. 212-222.
	AN	J. Bischoff et al., "New aspects of optical scatterometry applied to microtechnology", <i>SPIE</i> , Vol. 3215 (1997), pp. 144-155.
	AO	J. Bischoff et al., "Modeling of optical scatterometry with finite-number-of-periods gratings", <i>Part of the EUROPTO Conference on In-Line Characterization Techniques for Performance and Yield Enhancement in Microelectronic Manufacturing</i> , Edinburgh, Scotland, May 1999, SPIE Vol. 3743, pp. 41-48.
	AP	J. Bischoff et al., "Characterization of 3D resist patterns by means of optical scatterometry", <i>Part of the EUROPTO Conference on In-Line Characterization Techniques for Performance and Yield Enhancement in Microelectronic Manufacturing</i> , Edinburgh, Scotland, May 1999, SPIE Vol. 3743, pp. 49-60.
	AQ	J. Bischoff et al., "Light Diffraction Based Overlay Measurement", <i>Metrology, Inspection, and Process Control for Microlithography XV</i> , SPIE Vol. 4344 (2001), pp. 222-233.
	AR	T. Bosworth et al., "Critical-dimension and overlay metrology: a review", <i>Solid State Technology</i> , September 1995, pp. 119-123.
	AS	"Method for Measuring Semiconductor Lithographic Tool Focus and Exposure", <i>IBM Technical Disclosure Bulletin</i> , July 1987, pp. 516-518.
38	AT	"Interferometric Method of Checking the Overlay Accuracy in Photolithographic Exposure Processes", <i>IBM Technical Disclosure Bulletin</i> , Vol. 32, No. 10B, March 1990, pp. 214-217.

Examiner

Date Considered

Examiner Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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						YES	NO

OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

3/	AU	"Phase-Sensitive Overlay Analysis Spectrometry", <i>IBM Technical Disclosure Bulletin</i> , Vol. 32, No. 10A, March 1990, pp. 170-174.
	AV	"Interferometric Measurement System for Overlay Measurement in Lithographic Processes", <i>IBM Technical Disclosure Bulletin</i> , February 1994, pp. 535-536.
	AW	"Interferometric Method of Checking the Overlay Accuracy in Photolithographic Exposure Processes", <i>IBM Technical Disclosure Bulletin</i> , March 1990, pp. 214-217.
	AX	P. Heimann, "The Color-Box alignment vernier: a sensitive lithographic alignment vernier read at low magnification", <i>Optical Engineering</i> , July 1990, Vol. 29, No. 7, pp. 828-836.
	AY	"Layer Alignment/Overlay: Optical Diffraction", <i>Nerac.com Retro Search</i> , NERAC Inc., April 19, 2002, 93 pages in length.
	AZ	"Lateral Shift: Optical Methods/Techniques", <i>Nerac.com Retro Search</i> , NERAC Inc., April 19, 2002, 90 pages in length.
	BA	"Scatterometry and Overlay", <i>Nerac.com Retro Search</i> , NERAC Inc., April 19, 2002, 8 pages.
3/	BB	N. Blayo et al., "Ultraviolet-visible ellipsometry for process control during the etching of submicrometer features", <i>J. Opt. Soc. Am. A</i> , Vol. 12, No. 3, March 1995, pp. 591-599.
	BC	S. Sohail et al., "Optical Scatterometry for Process Metrology", <i>SPIE Vol. CR 72</i> (1999), pp. 129-143.

Examiner: <i>Salaw S</i>	Date Considered: <i>8/10/04</i>
Examiner's Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	